

**S/N 09/858238**

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

|             |  |                 |               |
|-------------|--|-----------------|---------------|
| Applicant:  | Tee O. Chong et al.  | Examiner:       | John Vigushin |
| Serial No.: | 09/858238  | Group Art Unit: | 2827          |
| Filed:      | May 15, 2001   | Docket:         | 884.419US1    |
| Title:      | ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS |                 |               |

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**INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(1) and 37 C.F.R. §1.97(e)(1), Applicants state that each item of information contained in the Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

It is believed that no fee or statement is required with the Information Disclosure Statement. However, if a final action under §1.113, a notice of allowance under §1.311, or an action that otherwise closes prosecution in the application has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

INFORMATION DISCLOSURE STATEMENT

Serial No :09/858238

Filing Date: May 15, 2001

Title: ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS

Assignee: Intel Corporation

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Dkt: 884.419US1 (INTEL)

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

TEE O. CHONG ET AL.

By their Representatives,

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Date May 28, 2003

By Ann M. McCrackin  
Ann M. McCrackin  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 28 day of May, 2003

Kacia Lee  
Name

Kacia Lee  
Signature



Substitute for form 1449A/PTO

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
(as many sheets as necessary)

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PTO/SB/08A(10-01)  
Approved for use through 10/31/2002. OMB 551-0031  
US Patent & Trademark Office: U.S. DEPARTMENT OF COMMERCE

Complete if Known

|                      |                |
|----------------------|----------------|
| Application Number   | 09/858238      |
| Filing Date          | May 15, 2001   |
| First Named Inventor | Chong, Tee     |
| Group Art Unit       | 2827           |
| Examiner Name        | Vigushin, John |

Sheet 1 of 1

Attorney Docket No: 884.419US1

**US PATENT DOCUMENTS**

| Examiner Initial * | USP Document Number | Publication Date | Name of Patentee or Applicant of cited Document | Class | Subclass | Filing Date If Appropriate |
|--------------------|---------------------|------------------|---|-------|----------|----------------------------|
|                    | US-4,495,377        | 01/22/1985       | Johnson, C. L., et al.                          | 174   | 68.5     | 12/30/1982                 |
|                    | US-6,310,398        | 10/30/2001       | Katz, W. M.                                     | 257   | 773      | 11/12/1999                 |

**FOREIGN PATENT DOCUMENTS**

| Examiner Initials* | Foreign Document No | Publication Date | Name of Patentee or Applicant of cited Document | Class | Subclass | T <sup>2</sup> |
|--------------------|---------------------|------------------|---|-------|----------|----------------|
|                    | EP-0883182          | 12/09/1998       | Horiuchi, M., et al.                            | H01L  | 23/523   |                |
|                    | EP-0921567          | 06/09/1999       | Horiuchi, M., et al.                            | H01L  | 23/498   |                |
|                    | EP-0928029          | 07/07/1999       | Horiuchi, M., et al.                            | H01L  | 23/538   |                |
|                    | EP-1071316          | 01/24/2001       | Horiuchi, M., et al.                            | H05K  | 1/18     |                |
|                    | EP-1075026          | 02/07/2001       | Horiuchi, M., et al.                            | H01L  | 23/498   |                |

**OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS**

| Examiner Initials* | Cite No <sup>1</sup> | Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published. | T <sup>2</sup> |
|--------------------|----------------------|---|----------------|
|                    |                      | DEHKORDI, P., et al., "Determination of Area-Array Bond Pitch for Optimum MCM Systems: A Case Study", <u>Proceedings of the IEEE Multi-Chip Module Conference, Los Alamitos, (Feb. 4, 1997), 8-12.</u>  |                |
|                    |                      | FJELSTAD, J., "Chip Scale Packages -- Their Future Impact on PCB Design", <u>Electronic Engineering, (Mar., 1998), 75-79.</u>   |                |

**EXAMINER****DATE CONSIDERED**

Substitute Disclosure Statement Form (PTO-1449)  
\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.<sup>1</sup> Applicant's unique citation designation number (optional) <sup>2</sup> Applicant is to place a check mark here if English language Translation is attached